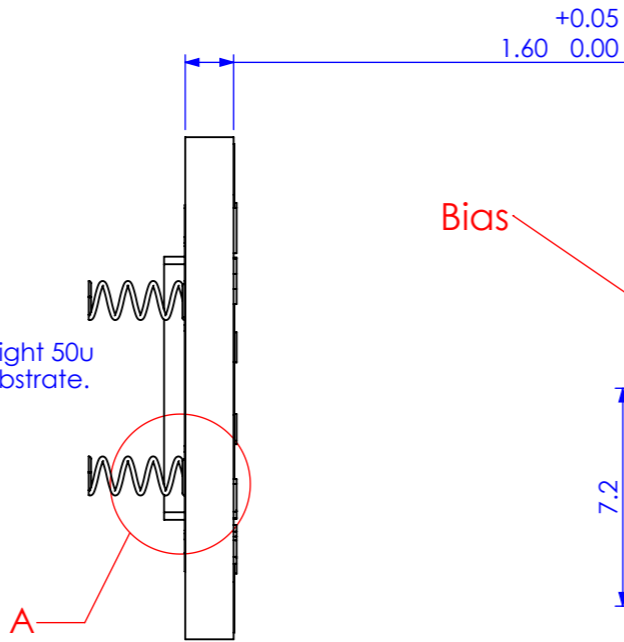
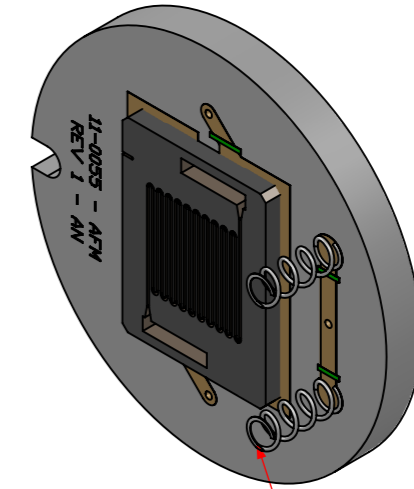
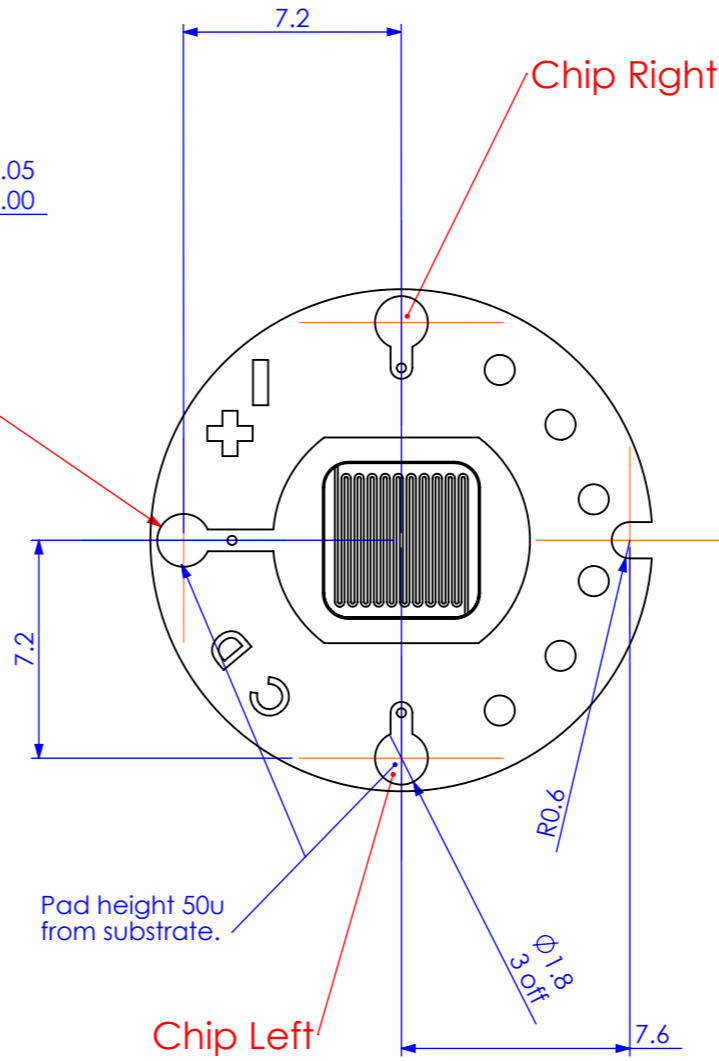


Pad height 50u from substrate.

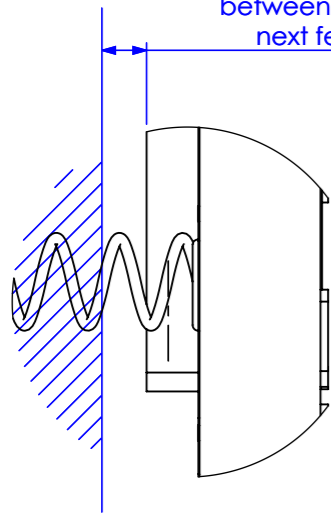


Bias



Contact Spring - 2 off

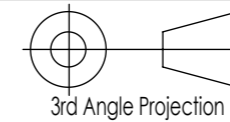
Required minimum distance between top of chip and next feature 1.0mm



DETAIL A  
SCALE 10 : 1

REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	DRAWN BY
E4	AAF	Further height info added to c.b. pads	28/07/2011	MH
E4	AAG	Liga chip shown	30/11/2011	MH
E4	AAH	Contact springs added. PCB Material Specified	01/10/2013	AJT

UNLESS OTHERWISE SPECIFIED  
ALL DIMENSIONS ARE IN mm.  
SURFACE FINISH: - Ra  
Tolerances  
Dim Precision Tolerance  
0. +/-0.5  
0.0 +/-0.1  
0.00 +/-0.01  
0.000 +/-0.001



3rd Angle Projection

FINISH:

DEBUR AND  
BREAK SHARP  
EDGES

DO NOT SCALE DRAWING

REVISION AAH

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	NAME	SIGNATURE	DATE
DRAWN	AJT		01/10/13
CHK'D			
APP'VD			
MFG			
Q.A			

MATERIAL:  
Rogers RO4350B

TITLE:	
FAIMS CHIP CARRIER	

DWG NO.	01-0181	A3
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